


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32F205RGT6V	PA5W*411XXX3	A	9998	13-09-2018
	Amount	UoM	Unit type	ST ECOPACK Grade
	307.98	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	PASW*411XXX3				6999999.0	999999.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.445	mg	supplier	die	Silicon (Si)	7440-21-3		9.945	mg	952130	32291
				supplier	metallization	Aluminium (Al)	7429-90-5		0.024	mg	2298	78
				supplier	metallization	Copper (Cu)	7440-50-8		0.211	mg	20201	685
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	96	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.068	mg	6510	221
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	287	10
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	191	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.054	mg	5170	175
LEADFRAME (MHT- C194)	M-011 Other inorganic materials	47.409	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.137	mg	13116	445
				supplier	ALLOY	Copper (Cu)	7440-50-8		46.200	mg	974503	150011
				supplier	ALLOY	Iron (Fe)	7439-89-6		1.138	mg	24002	3695
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.057	mg	1198	184
LEADFRAME (MHT- Ag)	M-011 Other inorganic materials	1.103	mg	supplier	ALLOY	Phosphorus (P)	7723-14-0		0.014	mg	297	46
				supplier	COATING	Silver(Ag)	7440-22-4		1.103	mg	1000000	3580
DIE ATTACH (Evertech -AP4200)	M-011 Other inorganic materials	0.009	mg	supplier	GLUE	Epoxy	9003-36-5		0.002	mg	222222	6
				supplier	GLUE	Silver(Ag)	7440-22-4		0.007	mg	777778	23
BONDING WIRE (MKE - Au wire)	M-011 Other inorganic materials	1.085	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		1.084	mg	999078	3520
				supplier	BONDING WIRE	Palladium (Pd)	7440-41-7		0.001	mg	922	3
ENCAPSULATION (Sumitomo -G631H)	M-011 Other inorganic materials	244.438	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Proprietary		25.384	mg	104237	82421
				supplier	MOLDING COMPOUND	Silica fused (SiO3)	60676-86-0		203.824	mg	833223	661807
				supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		13.961	mg	57329	45331
FINISHING - (ST380 -Sn)	M-011 Other inorganic materials	3.492	mg	supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		1.269	mg	5211	4120
				supplier	EXTERNAL PLATING	Tin (Sn)	7440-31-5		3.492	mg	1000000	11338